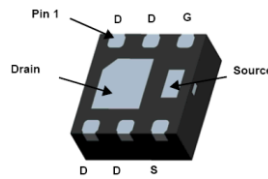
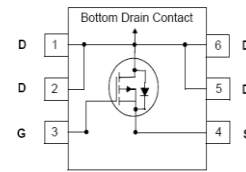


**Main Product Characteristics:**

$V_{DSS}$	-12V
$R_{DS(on)}$	14.4 m $\Omega$ (typ.)
$I_D$	-12A


**DFN2x2-6L Pin Assignment**

**Schematic diagram**
**Features and Benefits:**

- Advanced trench MOSFET process technology
- Special designed for battery charge, load switching in cellular handset and general ultraportable applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 150°C operating temperature


**Description:**

It utilizes the latest trench processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in battery charge and load switching in cellular handset and a wide variety of other ultraportable applications

**Absolute max Rating:**

Symbol	Parameter	Max.	Units
$I_D$ @ TC = 25°C	Continuous Drain Current, $V_{GS}$ @ 4.5V①	-12	A
$I_D$ @ TC = 100°C	Continuous Drain Current, $V_{GS}$ @ 4.5V①	-7.4	
$I_{DM}$	Pulsed Drain Current②	-28	
$P_D$ @TC = 25°C	Power Dissipation③	2.4	W
$V_{DS}$	Drain-Source Voltage	-12	V
$V_{GS}$	Gate-to-Source Voltage	± 8	V
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	°C

**Thermal Resistance**

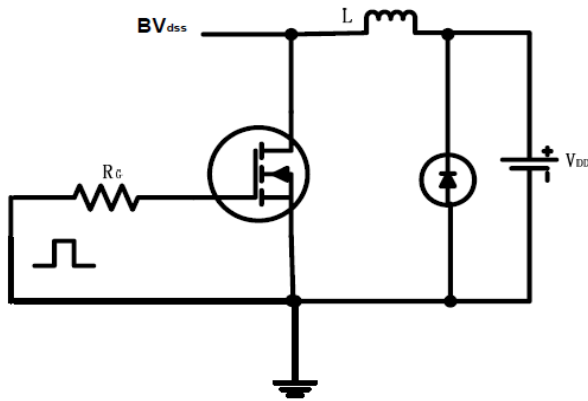
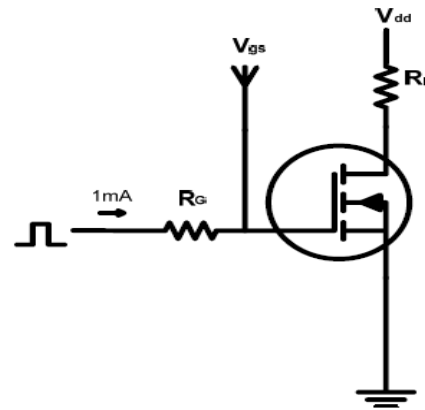
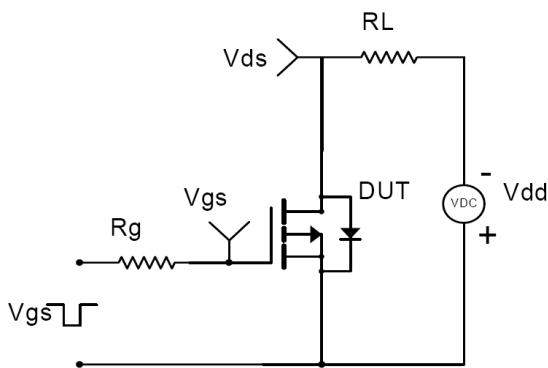
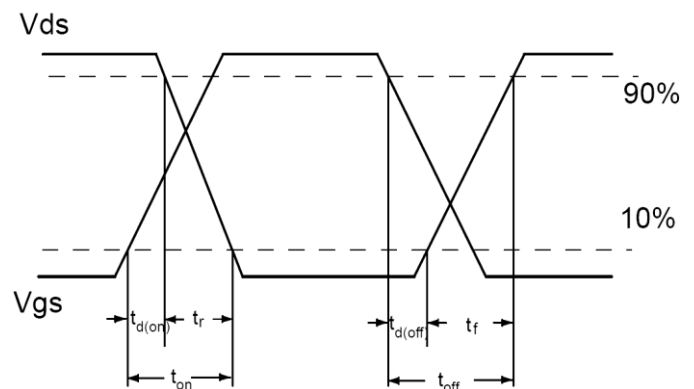
Symbol	Characterizes	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case	6.9	8	°C/W
$R_{\theta JA}$	Junction-to-ambient (t ≤ 10s) ④	52	62.5	°C/W

**Electrical Characterizes @ $T_A=25^{\circ}\text{C}$  unless otherwise specified**

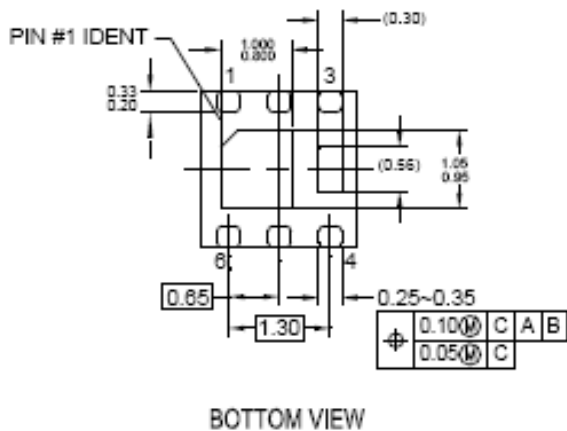
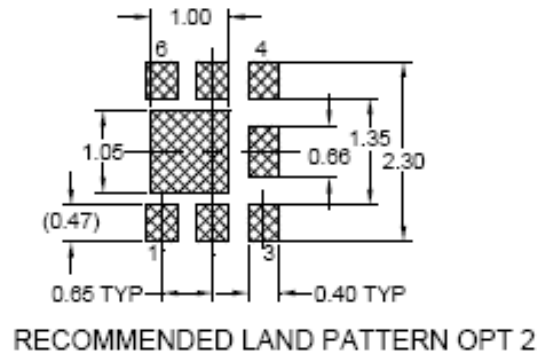
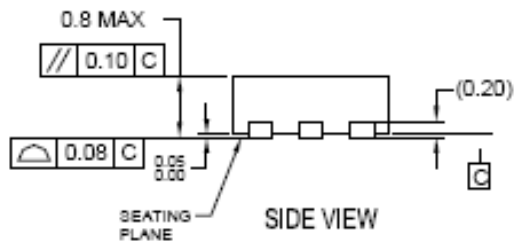
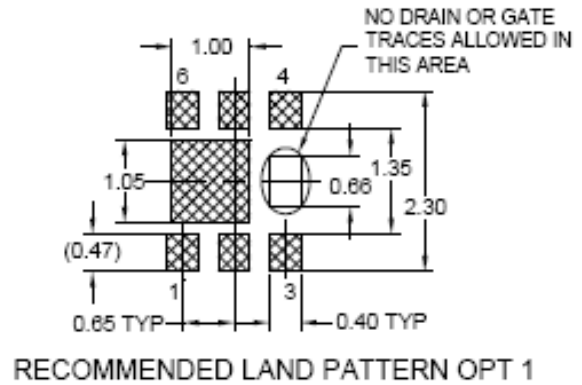
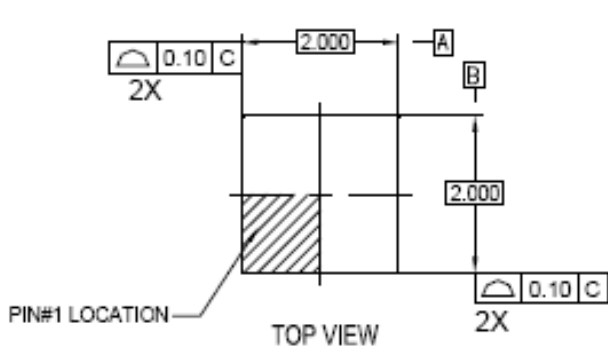
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	-12	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	14.4	16	m $\Omega$	$V_{GS} = -4.5V, I_D = -10A$
		—	18.9	21		$V_{GS} = -2.5V, I_D = -8.9A$
		—	26.4	38		$V_{GS} = -1.8V, I_D = -4.5A$
$V_{GS(th)}$	Gate threshold voltage	-0.4	—	-1	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
$I_{DSS}$	Drain-to-Source leakage current	—	—	-1	$\mu A$	$V_{DS} = -12V, V_{GS} = 0V$
$I_{GSS}$	Gate-to-Source forward leakage	—	—	100	nA	$V_{GS} = 8V$
		—	—	-100		$V_{GS} = -8V$
$g_{FS}$	Forward Transconductance	-3	—	—	S	$V_{DS} = -5V, I_D = -10A$
$Q_g$	Total gate charge	—	21	—	nC	$I_D = -10A,$ $V_{DD} = -6V,$ $V_{GS} = -4.5V$
$Q_{gs}$	Gate-to-Source charge	—	2.5	—		
$Q_{gd}$	Gate-to-Drain("Miller") charge	—	6	—		
$t_{d(on)}$	Turn-on delay time	—	30	—	ns	$V_{GS} = -4.5V,$ $V_{DD} = -6V,$ $I_D = -10A,$ $R_{GEN} = 6\Omega$
$t_r$	Rise time	—	48	—		
$t_{d(off)}$	Turn-Off delay time	—	97	—		
$t_f$	Fall time	—	65	—		
$C_{iss}$	Input capacitance	—	2138	—	pF	$V_{GS} = 0V$ $V_{DS} = -6V$ $f = 1MHz$
$C_{oss}$	Output capacitance	—	685	—		
$C_{rss}$	Reverse transfer capacitance	—	650	—		

**Source-Drain Ratings and Characteristics**

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	-12	A	MOSFET symbol showing the integral reverse p-n junction diode.
$I_{SM}$	Pulsed Source Current (Body Diode)	—	—	-28	A	
$V_{SD}$	Diode Forward Voltage	—	-0.77	-1.2	V	$I_S = -2A, V_{GS} = 0V$
$t_{rr}$	Reverse Recovery Time	—	16	—	ns	$T_J = 25^{\circ}\text{C}, I_F = -10A,$ $di/dt = 100A/\mu s$
$Q_{rr}$	Reverse Recovery Charge	—	5.9	—	$\mu C$	

**Test circuits and Waveforms**
**EAS test circuits:**

**Gate charge test circuit:**

**Switch time test circuit:**

**Switch Waveforms:**

**Notes:**

- ① The maximum current rating is limited by bond-wires.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation PD is based on max. junction temperature, using junction-to-ambient thermal resistance.
- ④ The value of  $R_{\theta JA}$  is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ C$
- ⑤ These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(MAX)} = 150^\circ C$ .

**Mechanical Data:**
**DFN 2 x 2-6L PACKAGE INFORMATION**

**Notes:**

- ① Does not fully conform to JEDEC registration MO-229 dated Aug/2003.
- ② Dimensions are in millimeters.
- ③ Dimensions and tolerances per ASME Y14.5M. 1994.

**Ordering and Marking Information**
**Device Marking: 1221**

**Package (Available)**  
**DFN 2x2-6L**  
**Operating Temperature Range**  
**C : -55 to 150 °C**

**Devices per Unit**

Package Type	Units/Tape	Tapes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
DFN2x2-6L	3000pcs	10pcs	15000pcs	4pcs	60000pcs

**Reliability Test Program**

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	$T_j=125^{\circ}\text{C}$ or $150^{\circ}\text{C}$ @ 80% of Max $V_{DSS}/V_{CES}/V_R$	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	$T_j=125^{\circ}\text{C}$ or $150^{\circ}\text{C}$ @ 100% of Max $V_{GSS}$	168 hours 500 hours 1000 hours	3 lots x 77 devices

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